

24. (*Unamended*) A tape carrier package semiconductor device, which has a tape carrier and semiconductor elements that have been packaged on the tape carrier, characterized in that said tape carrier comprises:

an insulating tape,

a metal wiring pattern installed on one surface of the insulating tape,

a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,

a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on a metal-wiring-pattern side of the tape,

a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side,

wherein the first and second insulating protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm² to 70 kgf/mm², and

wherein the solder resist of the first insulating protective film contains a filler that determines the viscosity thereof in the range of 10 wt% to 40 wt%.

25. (*Unamended*) A liquid crystal panel display, which is provided with a liquid crystal panel and a tape carrier package semiconductor device having a tape carrier and semiconductor elements that have been packaged on the tape carrier so as to drive the liquid crystal panel, characterized in that said tape carrier comprises:

an insulating tape,

a metal wiring pattern installed on one surface of the insulating tape,
a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,
a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on a metal-wiring-pattern side of the tape,
a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side,
wherein the first and second insulating protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm² to 70 kgf/mm², and
wherein the solder resist of the first insulating protective film contains a filler that determines the viscosity thereof in the range of 10 wt% to 40 wt%.

26. (*Unamended*) A tape carrier package semiconductor device, which has a tape carrier and semiconductor elements that have been packaged on the tape carrier, characterized in that said tape carrier comprises:

an insulating tape,
a metal wiring pattern installed on one surface of the insulating tape,
a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,
a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on a metal-wiring-pattern side of the tape,

a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side,

wherein the first and second insulating protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm² to 70 kgf/mm², and

wherein the first insulating protective film is made of solder resist of one kind, and the solder resist contains a filler which determines viscosity thereof in a range of 10 wt% to 40 wt%.

27. (*Unamended*) A liquid crystal panel display, which is provided with a liquid crystal panel and a tape carrier package semiconductor device having a tape carrier and semiconductor elements that have been packaged on the tape carrier so as to drive the liquid crystal panel, characterized in that said tape carrier comprises:

an insulating tape,

a metal wiring pattern installed on one surface of the insulating tape,

a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,

a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on a metal-wiring-pattern side of the tape,

a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side,